

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	15637	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:21
S2	1967	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:21
S3	586	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:22
S4	341	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:22
S5	109	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:22
S6	69	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:22
S7	53	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:23
S8	43	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:23

S9	41	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:24
S10	0	resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder and (438/585.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/08/31 08:23